

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:25
L2	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:26
L3	5	("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:25
L4	6	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L5	6	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L6	10757	lead with bump ssame solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L7	4420	lead with bump ssame solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:27
L8	16	lead with bump same solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:27
L9	4	("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:30
L10	33	("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:38
L11	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:39
L12	38	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2005/10/15 21:40
L13	13	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2005/10/15 21:40
L14	33	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2005/10/15 21:40
L15	75	12 13 14	USPAT	OR	ON	2005/10/15 21:41
L16	75	12 13 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:41
L17	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42

L18	2608	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 21:42
L19	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L20	0	L19 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L21	338	L18 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L22	258	L18 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L23	65	L22 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L24	157	("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L25	40	L18 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L26	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L27	1996	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L28	484	L27 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L29	11	("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42

L30	5	(US-6445075-\$ or US-6576495-\$ or US-6661104-\$ or US-6724091-\$ or US-6819004-\$).did.	USPAT	OR	ON	2005/10/15 21:42
L31	121	lead with substrate with bump and 257/778.ccls.	USPAT	OR	ON	2005/10/15 21:42
L32	5	("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L33	21	("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L34	16	("4706811" "4758407" "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L35	81	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2005/10/15 21:42
L36	81	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2005/10/15 21:42